

SUSS MICROTEC INVESTOR PRESENTATION

March 2012

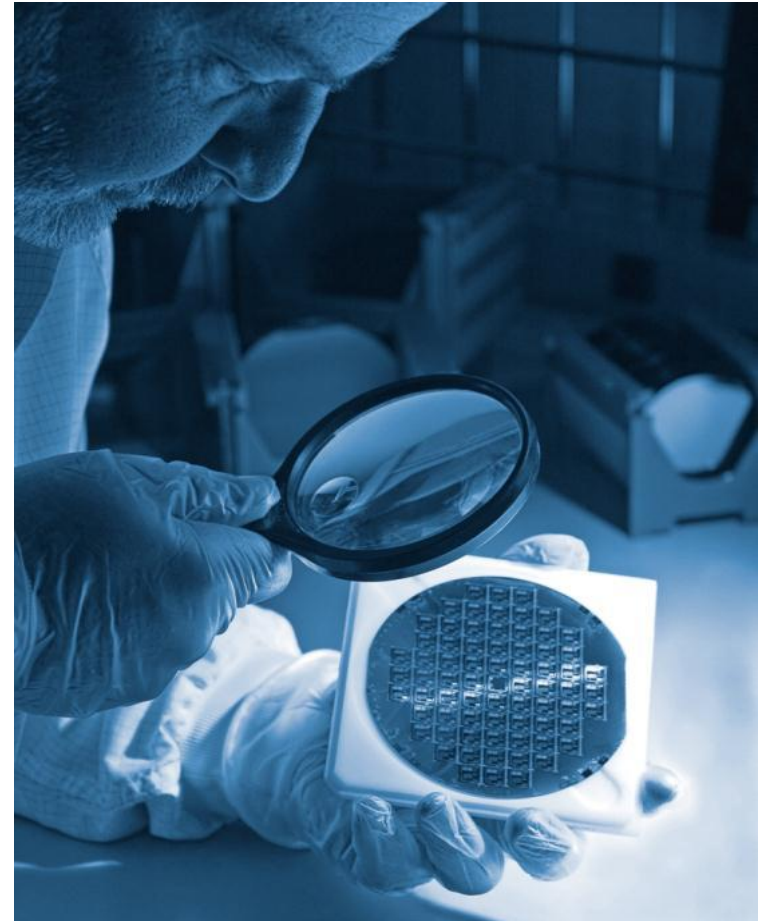
This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

- I. SUSS MicroTec at a Glance**
- II. Products and Markets
- III. Growth Opportunities
- IV. Financials
- V. Outlook

- + SUSS MicroTec: A global leader in semiconductor equipment
- + Our equipment and process solutions create the micro structures that build and connect micro electronic devices
- + We are focused on high growth market segments: Semiconductors, MEMS, LEDs

+ Key Data:

- Stock Exchange Symbol: SMHN
- TecDAX
- Share price*: 10.6 €
- Market Cap*: 203 € million
- Net Cash, 2011: 42.0 € million



* February 29, 2012



Garching

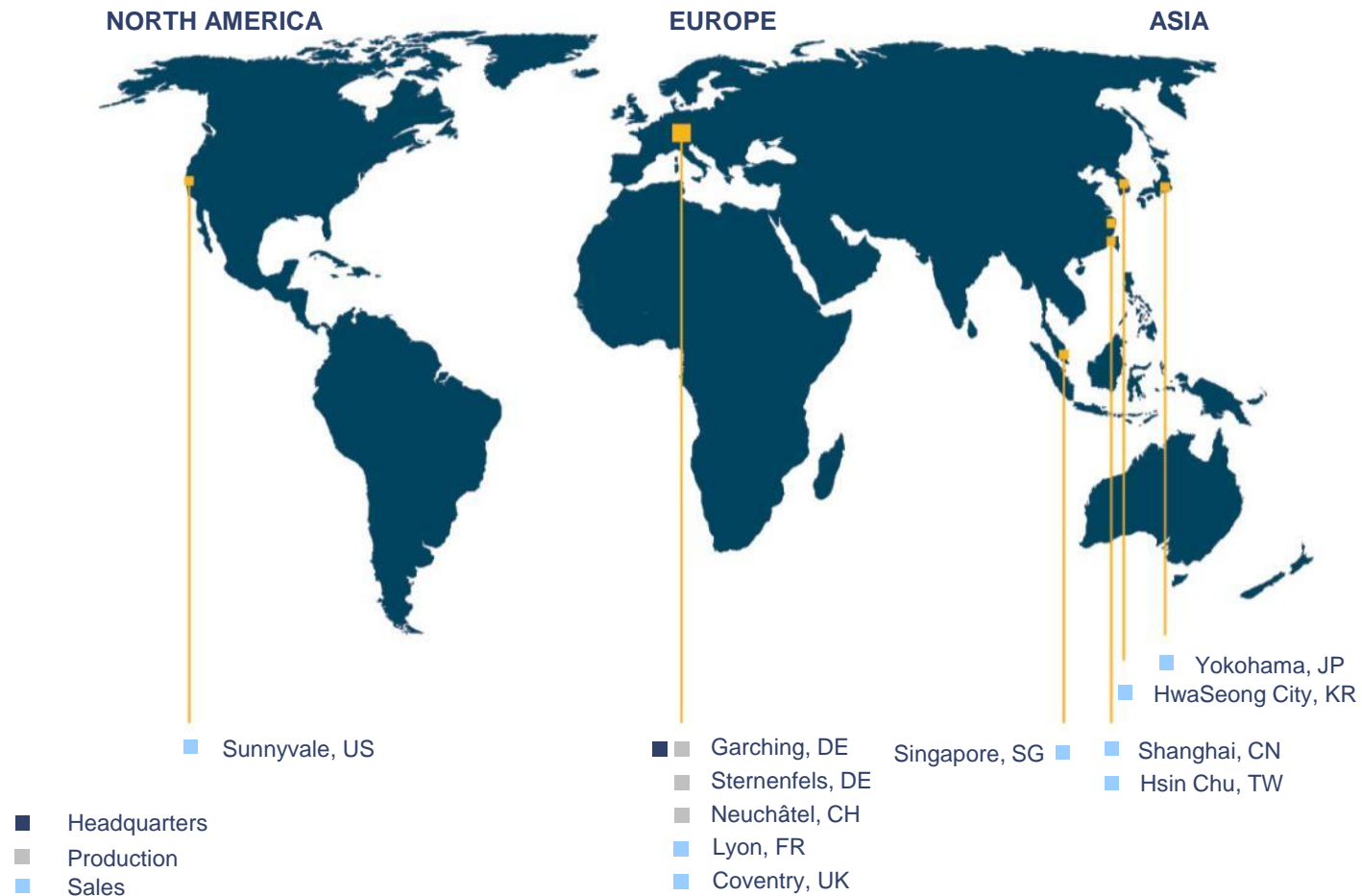
- + SÜSS MicroTec AG HQ
- + Development and production:
 - Mask Aligner
 - Bond Aligner
- + Core competencies:
 - Exposure
 - Alignment



Sternenfels

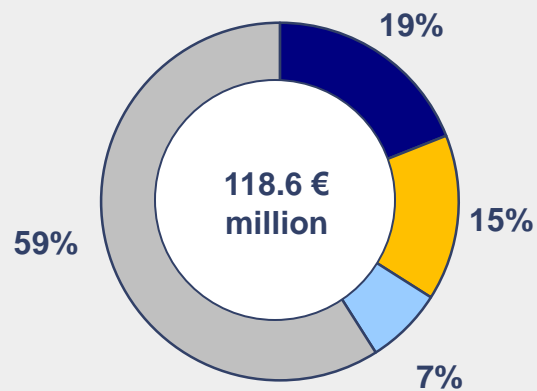
- + Development and production :
 - Bonder
 - Coater and Developer
 - Photomask Equipment
- + Core competencies:
 - Wet processing
 - Wafer bonding

SUSS MICROTEC – A GLOBAL PLAYER



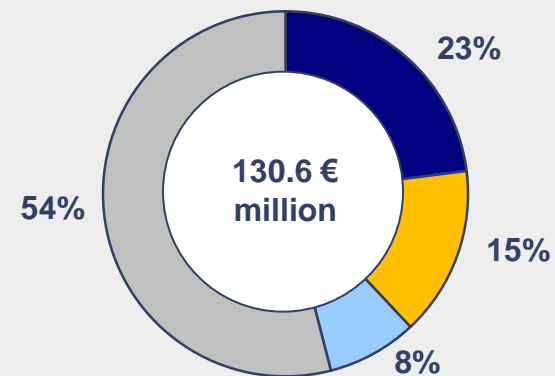
ORDER INTAKE AND SALES BY REGION 9M 2011

Order Intake



■ Europe	22.0 € million
■ North America	17.4 € million
■ Japan	8.4 € million
■ Rest of Asia	70.7 € million

Sales



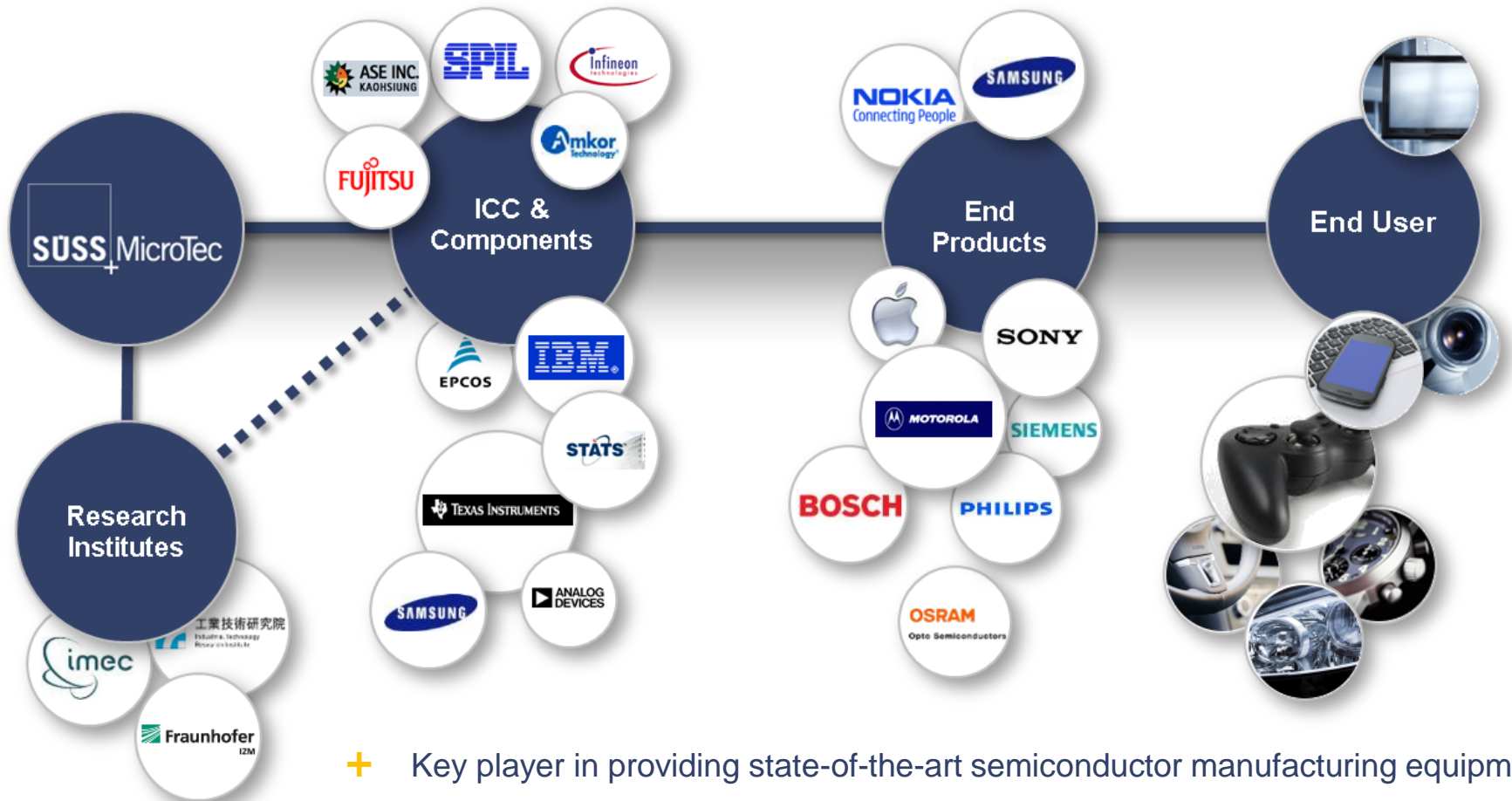
■ Europe	30.0 € million
■ North America	20.0 € million
■ Japan	9.8 € million
■ Rest of Asia	70.8 € million

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SUSS MICROTEC IN THE VALUE CHAIN

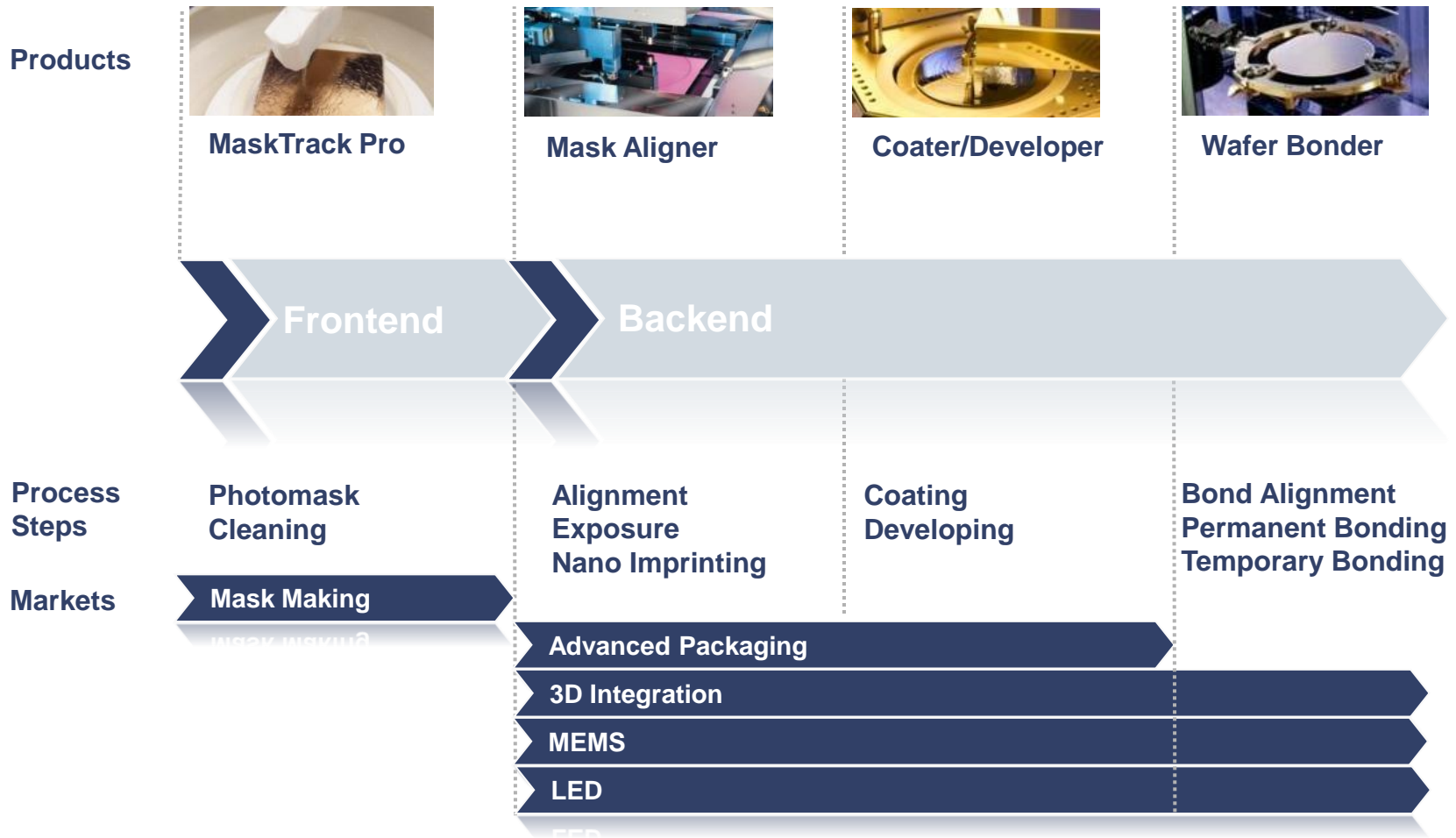


- + Key player in providing state-of-the-art semiconductor manufacturing equipment
- + Development of highly innovative systems with industry and R&D partners
- + Components for cell phones, PCs and tablet computers are produced on SUSS MicroTec's equipment

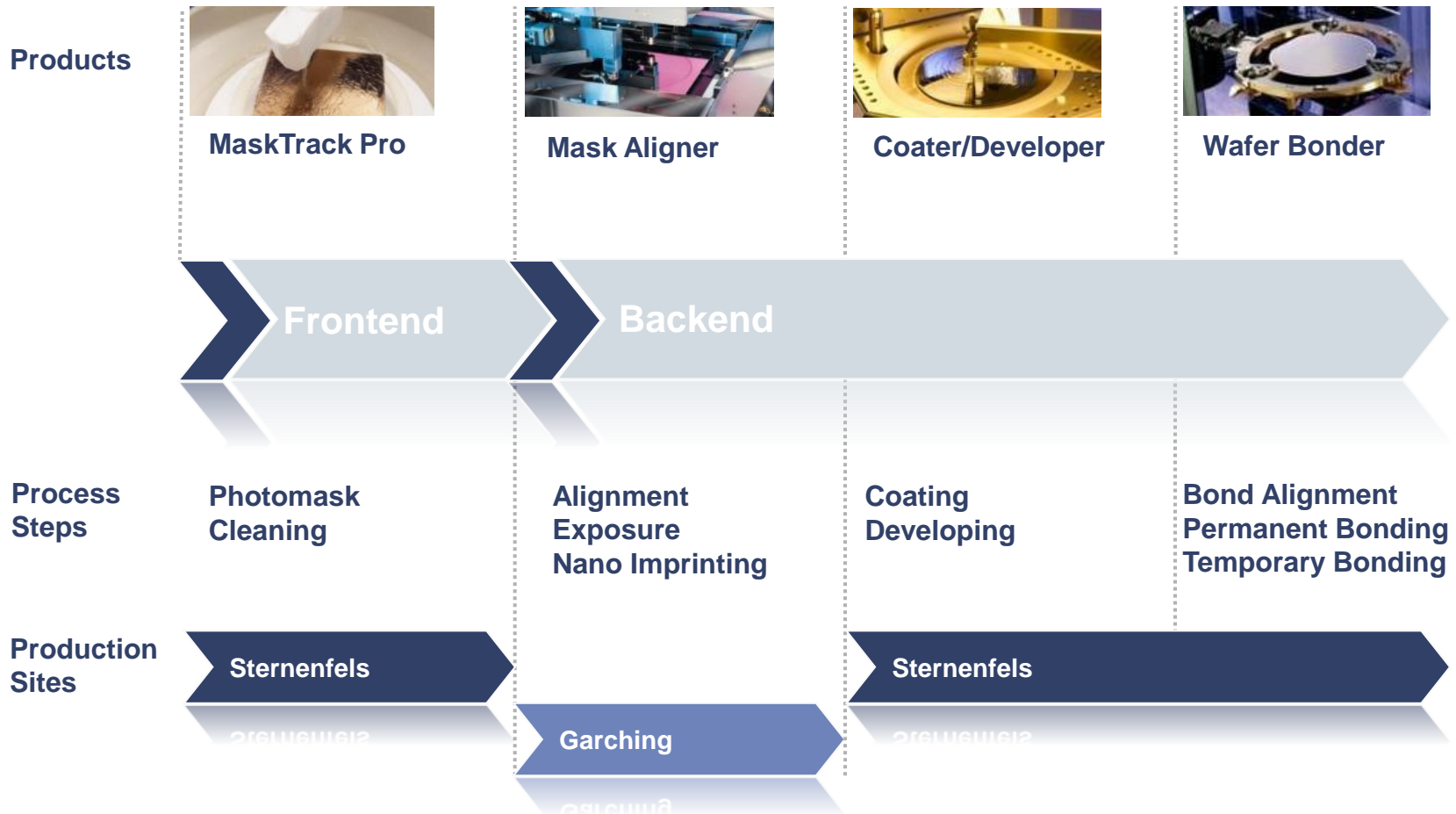
SEGMENTS AND PRODUCTS

Segments	Photomask Equipment	Lithography		Substrate Bonder
Products	 MaskTrack Pro	 Mask Aligner	 Coater/Developer	 Wafer Bonder
<div> <div>Frontend</div> <div>Backend</div> </div>				
Process Steps	Photomask Cleaning	Alignment Exposure Nano Imprinting	Coating Developing	Bond Alignment Permanent Bonding Temporary Bonding
Key figures 9M 2011	Sales: 25.8 € million EBIT: 4.4 € million	Sales: 84.4 € million EBIT: 20.0 € million		Sales: 14.8 € million EBIT: -7.7 € million

SEGMENTS AND MARKETS



SEGMENTS AND PRODUCTION SITES



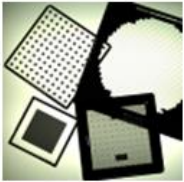
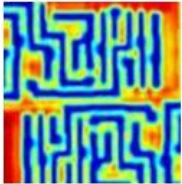
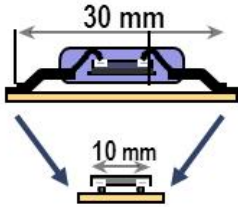
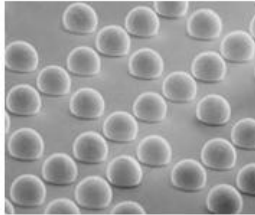
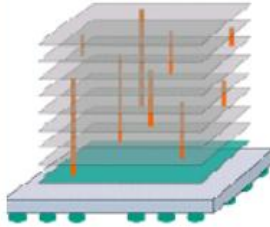
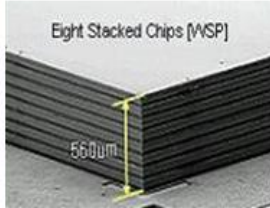

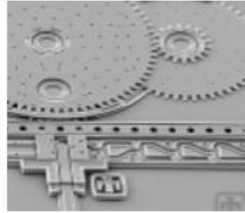
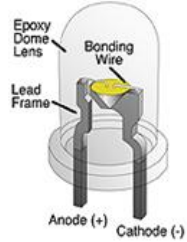

Semiconductors			Sensors	Lighting
Mask Making Photomask Cleaning	Advanced Packaging Micro-Bumping	3D Integration/Stacking	MEMS Computing, Automotive, Medical Applications ...	LED General Lighting, HB and UHB LED
 	 	 	 	 

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V. Outlook

- + Global mega-trends drive the microelectronics industry and create long term opportunities
 - **Digital Lifestyle**
 - **E-Mobility**
 - **Energy efficiency**
- + Micro chips, MEMS und LEDs are the building blocks for the technological product advancement
- + SUSS MicroTec's focus is to offer development and manufacturing solutions for these components in markets that have a sustainable long term growth perspective



Digital lifestyle



E-mobility

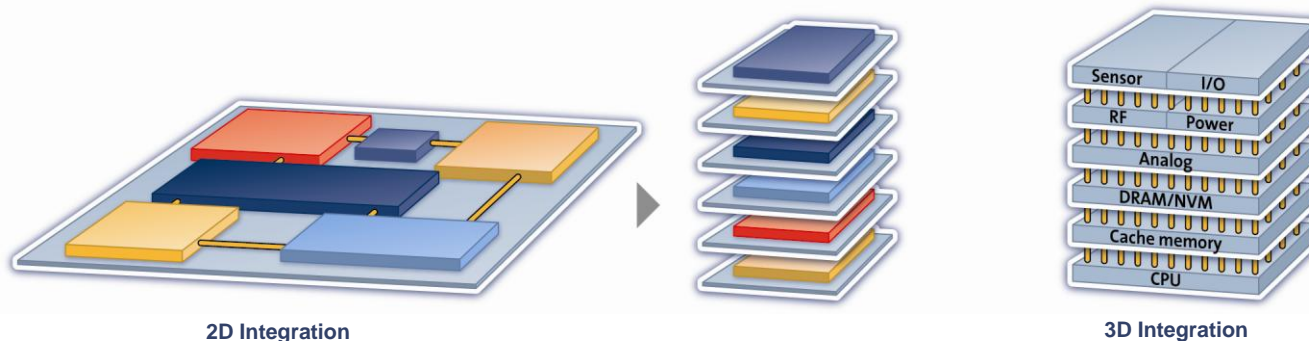


Energy efficiency

- + The further increase in complexity and performance of future semiconductor device generations demands the continuous progress in scaling of these devices
- + SUSS MicroTec's equipment and process solutions enable the 2-dimensional reduction of feature sizes ("Moore's Law") as well as the 3-dimensional stacking of integrated circuits ("More than Moore")

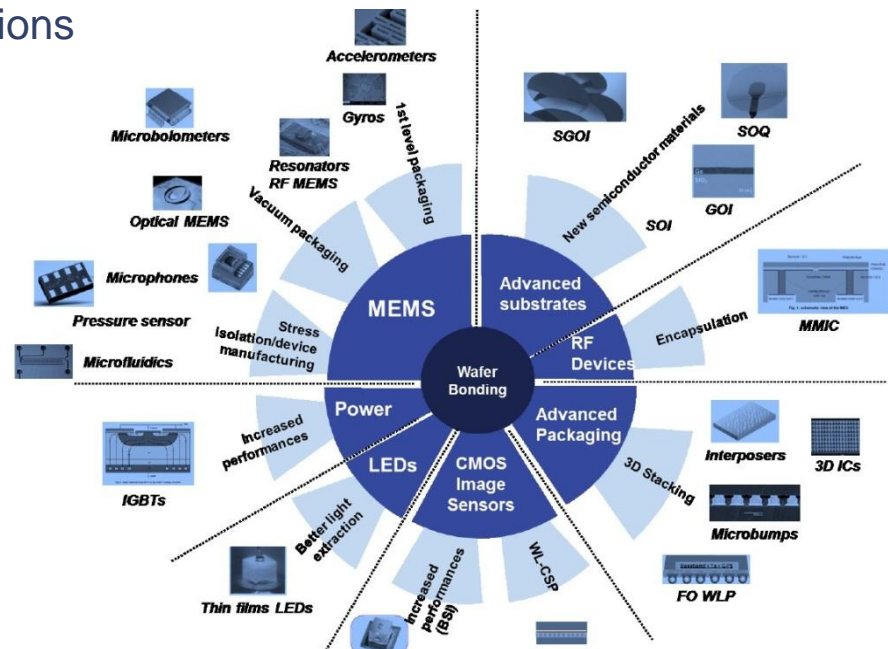


- + Technical challenges and limitations make it increasingly more expensive to pursue the shrink roadmap of integrated circuits
- + While alternatives like 3D integration promise greater space efficiency, lower power consumption and a significant increase in performance they will not replace shrinking



- + For the years to come shrinking and stacking technologies will coexist, each having its unique set of challenges
- + SUSS MicroTec is one of the few companies offering production equipment and process solutions for 2-dimensional and 3-dimensional scaling

- + The company's long term growth perspective derives from the double digit growth rates of the target markets 3D Integration, Advanced Packaging, LED and MEMS
- + SUSS MicroTec is one of the leading suppliers for wafer bonders in the semiconductor industry offering a broad portfolio of permanent and temporary bonding equipment and process solutions
- + The wafer bonder equipment market is estimated to grow rapidly to a size of larger 500 million \$ within the next few years
- + SUSS MicroTec targets a market share of 30%+ which is in line with the current market position



Source: Yole Développement

OVERVIEW ON TEMPORARY BONDING: TRADITIONAL VS. NEW PROCESSES

New Trend:

Mechanical Room Temperature Release / Release Layer Approaches



Material made by **WACKER**



SUSS XBC300



ZoneBOND™


Traditional Methods:

Thermal Slide




WaferBOND™

Laser Release



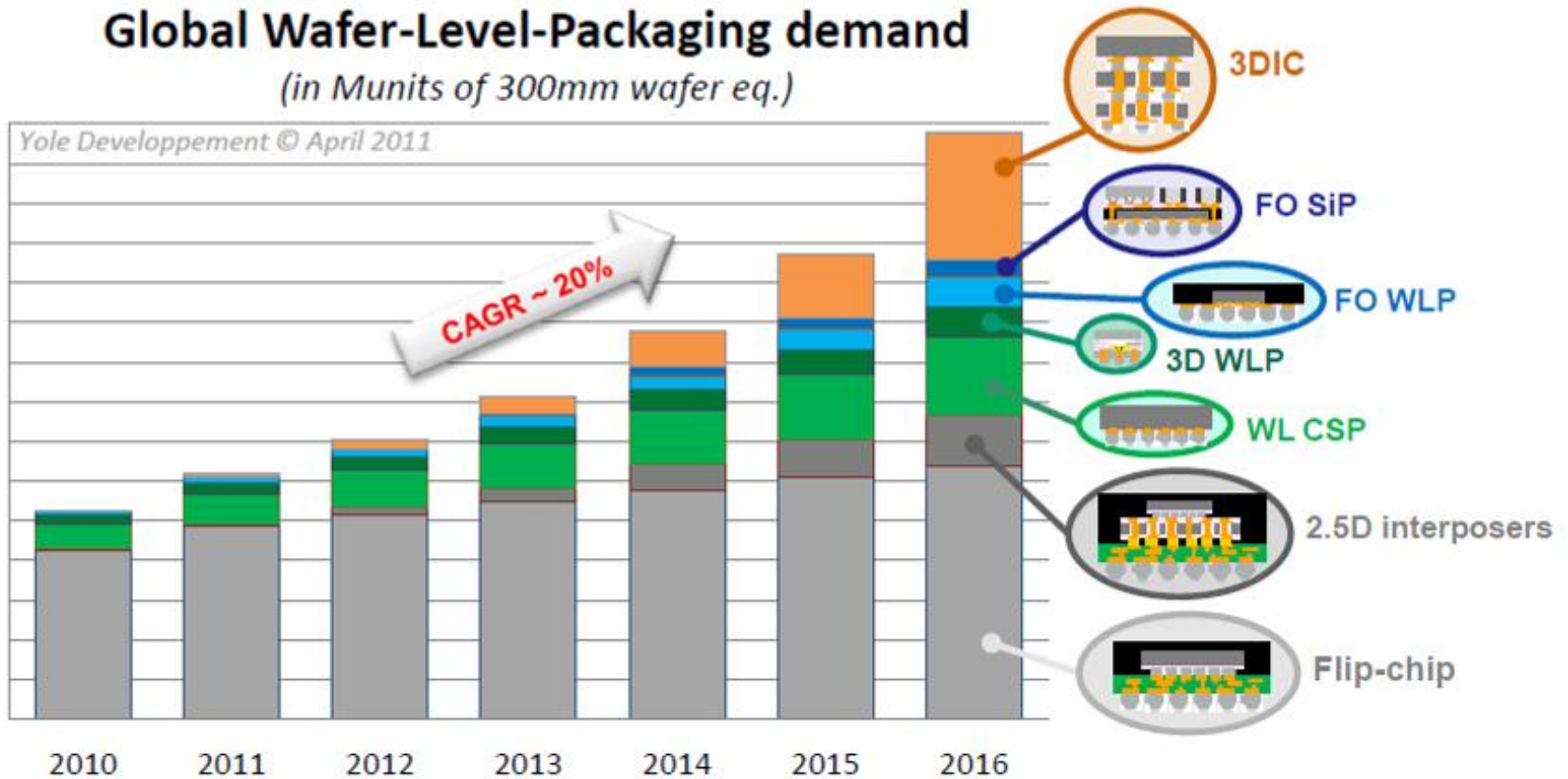
Wafer Support System



The miracles of science™
HD-3007

Global Wafer-Level-Packaging demand (in Munits of 300mm wafer eq.)

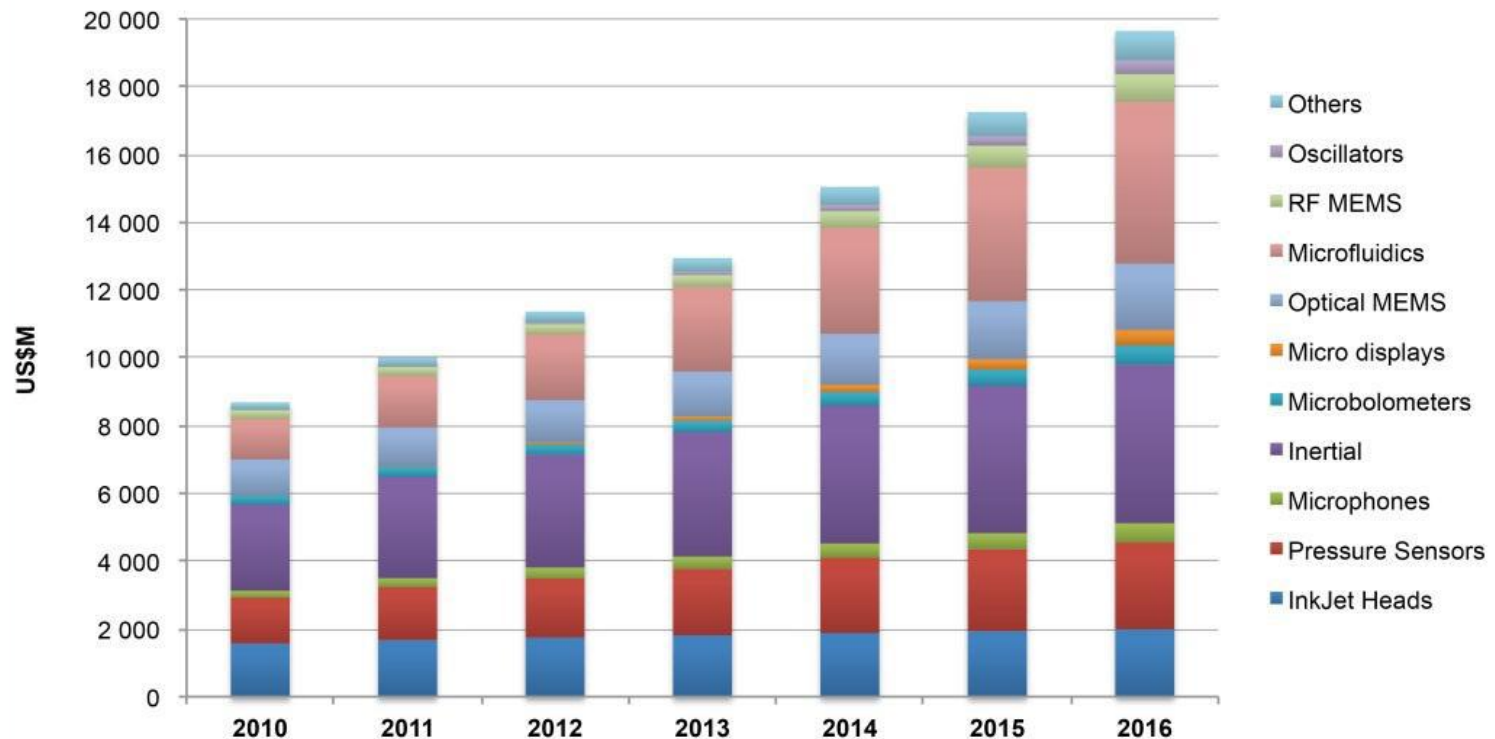
Yole Developpement © April 2011



Source: Yole Developpement

2010-2016 MEMS markets forecast (in US\$M)

(Source : Status of the MEMS Industry Report, 2011)



© September 2011

Source: Yole Développement



- + Three product lines under one roof
 - Photomask Equipment - Coater / Developer - Bonder
- + Modern production facility (15,000 m²) with two large clean rooms supporting future business expansion

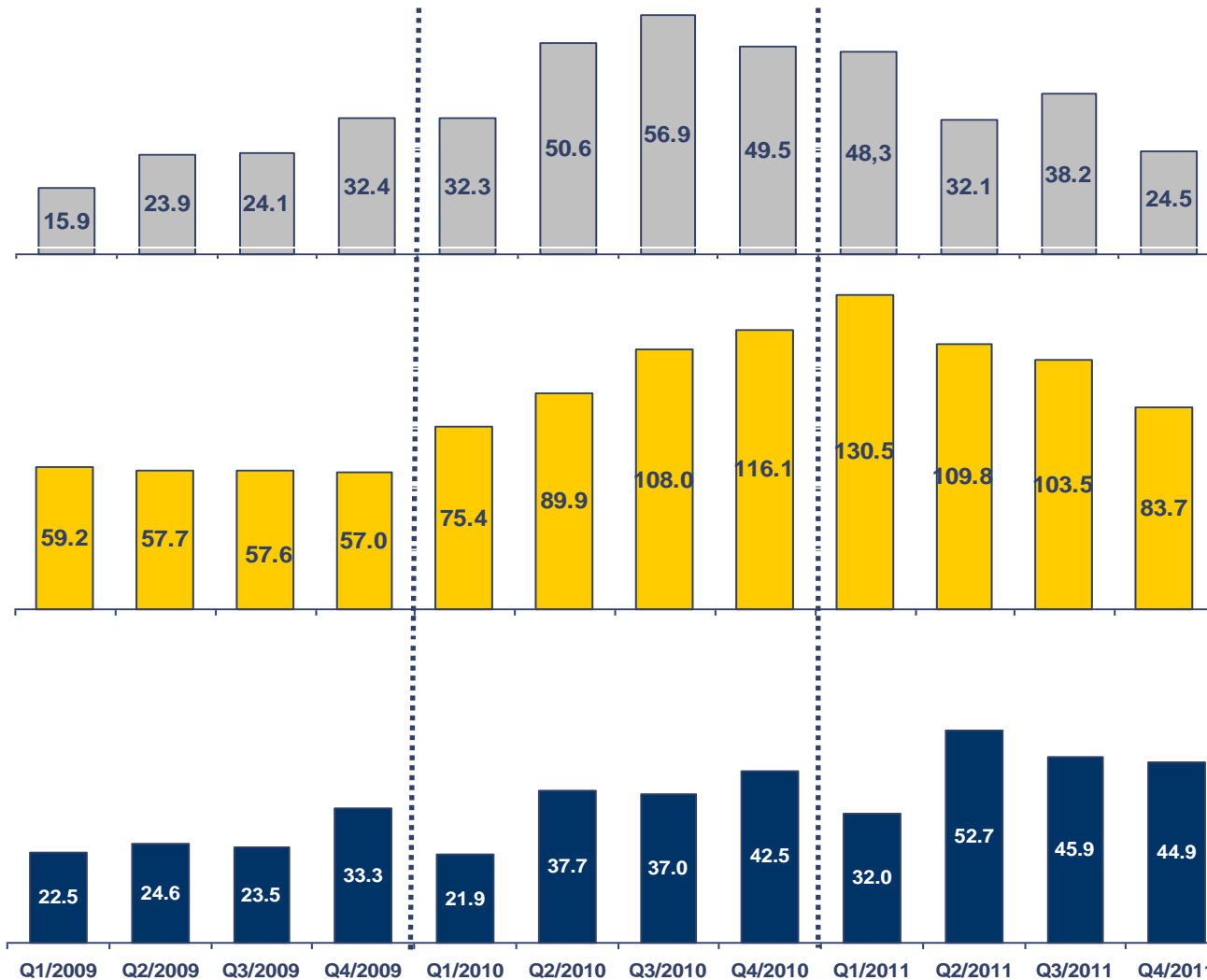


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36 MONTHS BUSINESS DEVELOPMENT

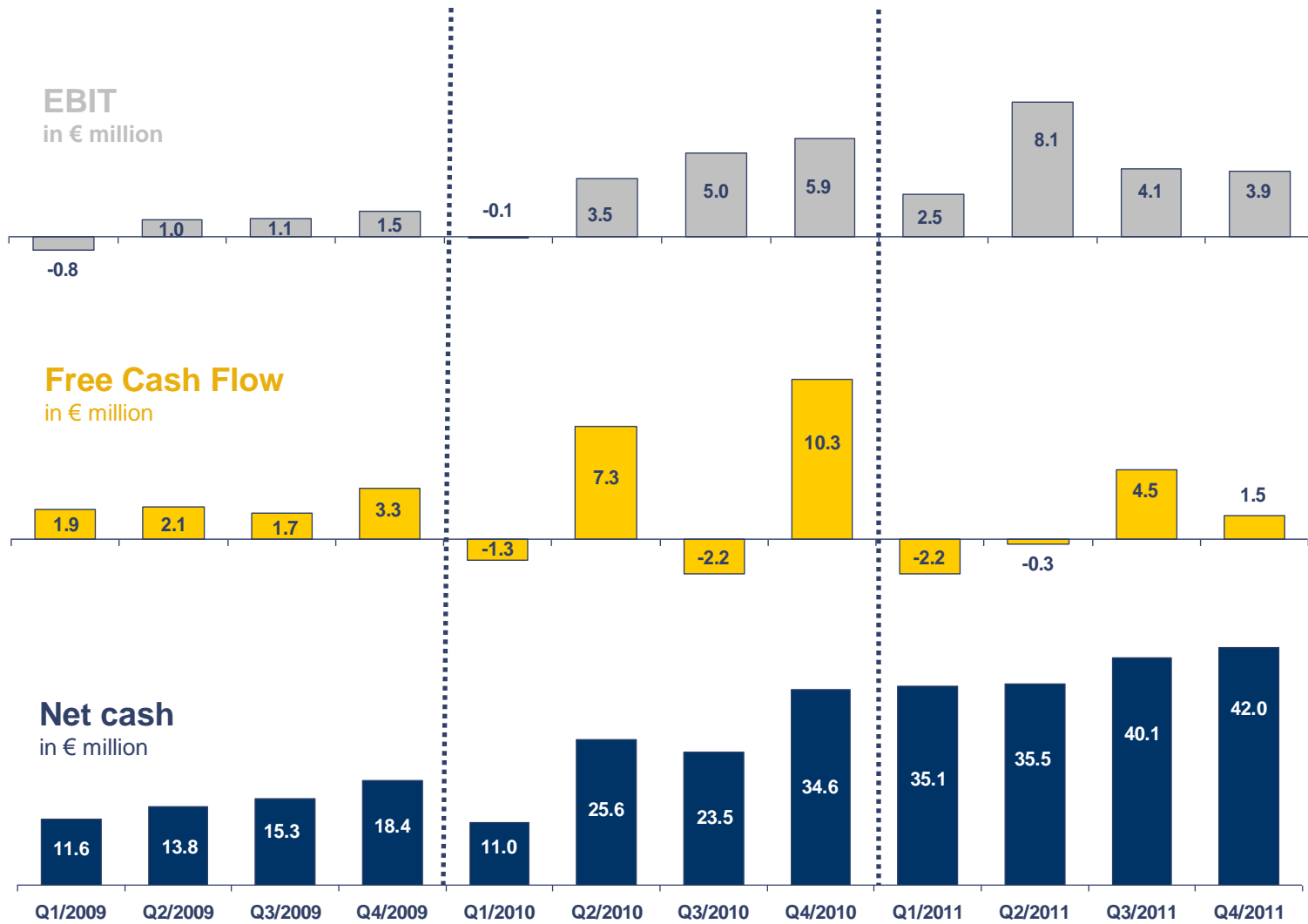


Order Entry
in € million

Order Backlog
in € million

Sales
in € million

EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



KEY FINANCIALS

in € million	2011	2010	in %
Order Intake	143.1	189.3	-24%
Order Backlog (12/31)	83.7	116.1	-28%
Revenue	175.4	139.1	26%
EBIT	18.6	14.3	30%
<i>EBIT in % of Sales</i>	<i>10.6%</i>	<i>10.3%</i>	<i>0.3% pt</i>
Free Cash Flow*	3.5	14.1	-75%
Net Cash**	42.0	34.1	23%

* Before consideration of purchase or sale of available-for-sale securities and before consideration of extraordinary items from purchase or sale of subsidiaries

** incl. interest-bearing securities

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Investment Case

- + Strong competitive positioning:
first or second in the target markets
- + Expansion of the solid financial situation and increasing profitability
- + Strong fundamental growth in target markets
- + Significant mid term revenue opportunity
- + Evolve to a leading company in the semiconductor backend, enabling 3D integration while supporting “Moore’s Law” as well as “More than Moore”
- + Participate in the consolidation of the backend



Thank you!

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